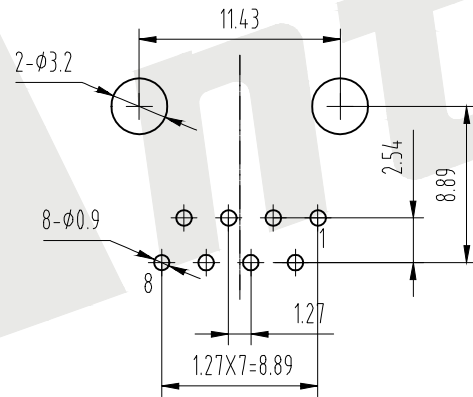
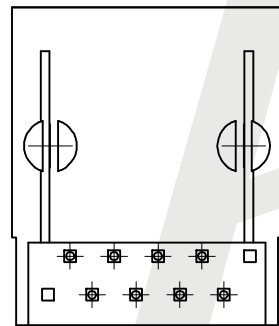
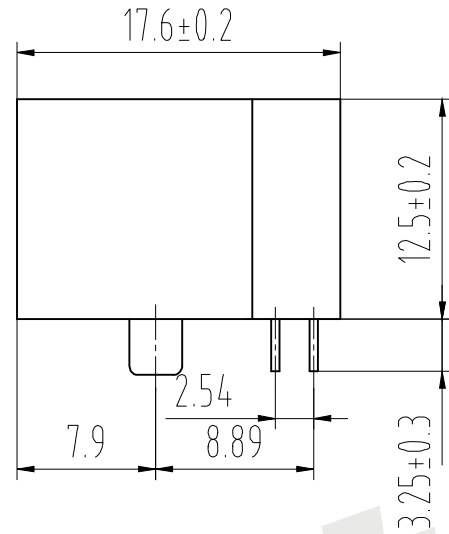
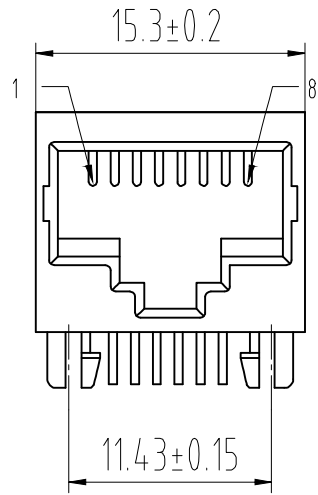


HSF



ROHS



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE t=0.3mm
3. PLATING: SELECTING GOLD PLATING 1 μ~50 μ" OVER NICKEL IN CONTACT AREA. 150 μ" TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE ELECTRICAL
1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTION PRB-SOLDER: 1 LB MIN REVRONMENTAL
1. STORAGE: -40° C TO 85° C
2. OPERATION: 0° C TO 70° C

Order code:

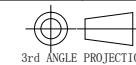
ATRJ5621 - 10P - 8C - X - A - A

① ② ③ ④ ⑤ ⑥

- | | |
|-----------------------------------------|--------------------|
| ① SERIES NO: | ⑤ Shield |
| ② NUMBER OF POSITIONS (10P, 8P, 6P, 4P) | A: W/O Shield |
| ③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C) | B: Half Shield |
| ④ Contact Plating | C: Shield W/Eml |
| G0: Gold flash | D: Shield W/O Eml |
| G1: 3U" Gold | ⑥ Ports |
| G2: 5U" Gold | A: 1X1P G: 2X1P |
| G3: 10U" Gold | B: 1X2P H: 2X2P |
| G4: 15U" Gold | C: 1X4P I: 2X3P |
| G5: 30U" Gold | D: 1X5P J: 2X4P |
| SN: Tin | E: 1X6P K: 2X6P |
| | F: 1X8P L: 2X8P |

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018



Antenk® ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: RJ45 JACK Side entry,
Full Plastic 1X1P

DRAWING NO: ATRJ5621-10P8C-X-A-A

PRODUCT NO: ATRJ5621-10P8C-X-A-A

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		